

PRODUCT DATA SHEET

K-859 5 MIL POLYIMIDE FILM TAPE

APPLICATIONS

K-859 consists of polyimide film and acrylic adhesive designed for die-cut high temperature masking dots. Used for protection of printed circuit boards during wave soldering. K-859 is also used in electrical insulation applications meeting class H requirements.

FEATURES/BENEFITS

- Wide operating temperature range up to 400°F
- The high temperature polyimide film absorbs heat without shrinking or losing its construction integrity.
- Removes cleanly without adhesive residue after exposure to heat/chemicals.
- Excellent electrical insulation.

TECHNICAL DATA

Backing material : 5 mil Polyimide Film Adhesive : Acrylic Adhesive

Color : Amber
Adhesive Thickness : 1.5 mils

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Adhesion to steel : 600 (gram/inch)
Tensile strength : 45 (kg/inch)
Dielectric Strength : 22,000 volts

Temperature Resistance : 200°C Insulation Class : 180

Note: The above are typical values obtained from tests recommended by the PSTC, ASTM, or government agencies and should not be used in writing specifications.